

## ABSTRACT OF THE DISCLOSURE

A semiconductor chip is produced through dicing without removing a conductive film for forming an interconnection and the like from a dicing line region. A prescribed insulating sheet member is adhered to this  
5 semiconductor chip at its back face, and the back face and the side face of semiconductor chip, and part of a front face along the periphery of semiconductor chip are covered by insulating sheet member. Thus, even when the conductive film in the dicing line region is curled up by dicing and a burr is resulted at the periphery of semiconductor chip, burr is covered by  
10 insulating sheet member to prevent a wire and burr from directly contacting to each other. Thus, a semiconductor device in which an electrical short circuit is prevented without removing a conductive film from a dicing line can be obtained.